

[MULTI-CHIP PACKAGE]

Abstract

A multi-chip package structure is provided. The multi-chip package comprises a first chip, a second chip, a plurality of bumps and a plurality of contacts. The first chip has an active surface. The second chip is mounted on the active surface of the first chip and the height of the second chip in a direction perpendicular to the active surface of the first chip is defined as h_1 . The bumps are positioned between the active surface of the first chip and the second chip and the height of the bumps in a direction perpendicular to the active surface of the first chip is defined as h_2 . The contacts protrudes from the active surface of the first chip and the height of the contacts in a direction perpendicular to the active surface of the first chip is defined as h_3 . The values of h_1 , h_2 and h_3 are related by the inequality: $h_3 \geq h_1 + h_2$.